



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



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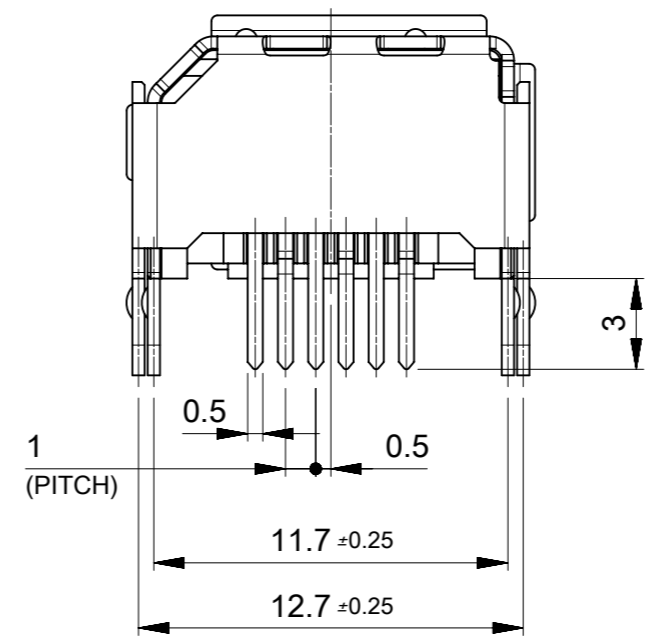
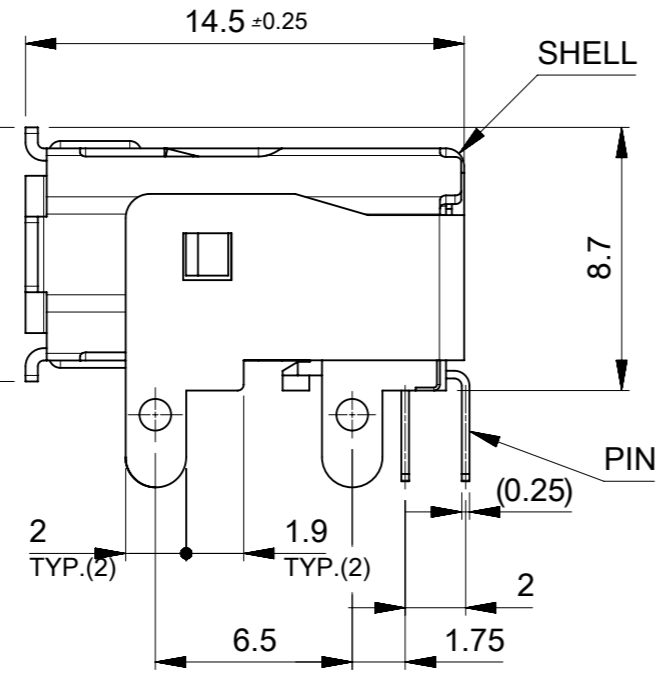
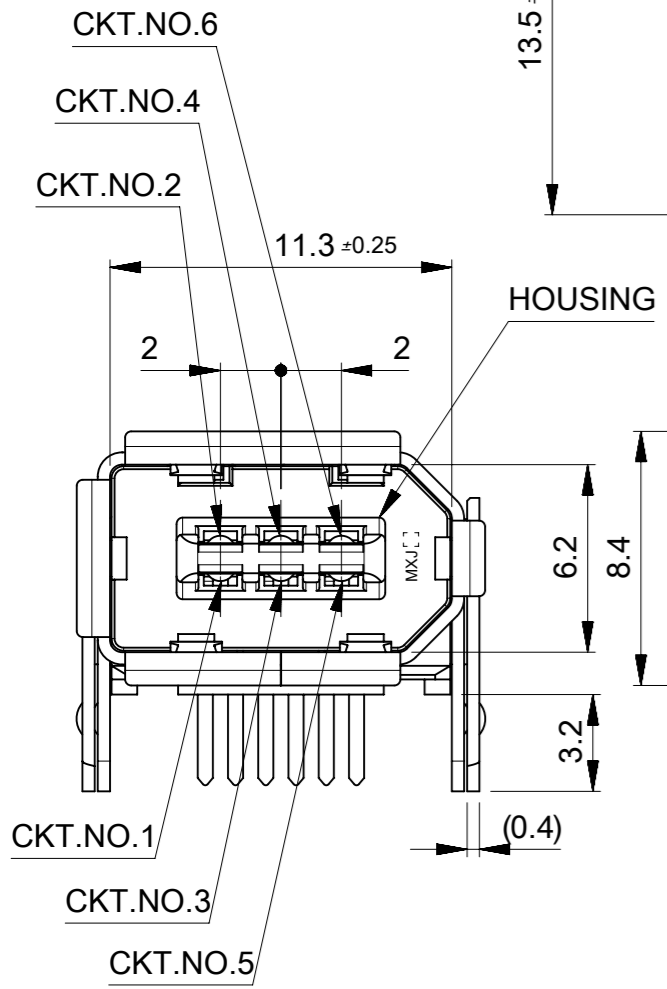
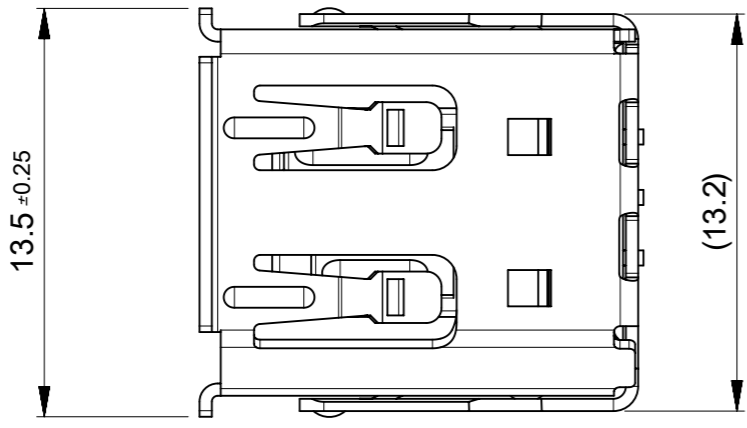
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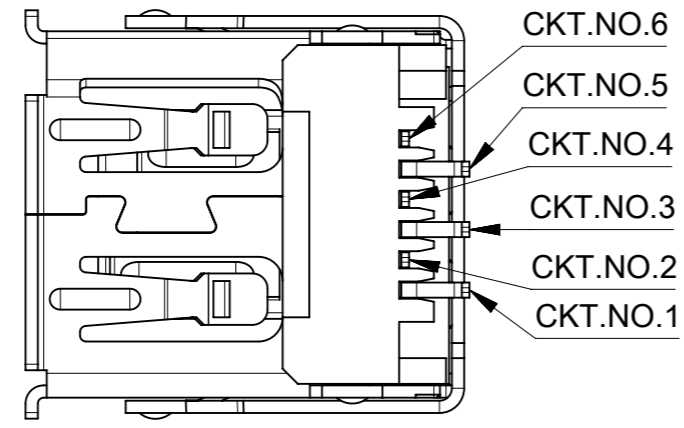
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部品名 WAFER	材質 MATERIAL	記事 ARTICLE
ハウジング HOUSING	ガラス入り耐熱樹脂 G.F.HEAT RESISTANT PLASTIC	UL94V-0, 色:黒 UL94V-0, COLOR:BLACK
ピン PIN	黄銅 t0.25 BRASS t0.25	接点部:金メッキ0.76μm MIN. CONTACT AREA:GOLD 0.76μm MIN. 半田付け部:錫メッキ1.0μm MIN. SOLDERTAIL AREA:TIN 1.0μm MIN. 下地メッキ:ニッケルメッキ 2.0μm MIN. UNDER-PLATING:NICKEL 2.0μm MIN.
シェル SHELL	りん青銅 t0.4 PHOSPHOR BRONZE t0.4	錫メッキ:1.0μm MIN.* TIN:1.0μm MIN. 下地メッキ:ニッケルメッキ 1.27μm MIN.* UNDER-PLATING:NICKEL 1.27μm MIN.

※半田付け部のみ。
ONLY SOLDERING PART.



注記:
NOTES:
1. 本製品は53984-0671のリフローディップ対応品である。
THIS PRODUCT IS REFLOW DIP VERSION OF 53984-0671.



6	53984-0681	53984-**81
CKT	MATERIAL NO.	MODEL NO.

SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC:			molex			
	DIMENSION UNITS	SCALE							2.0 I/O SOCKET RIGHT ANGLE -LEAD FREE-
	▽ = 0	mm	4:1	EC NO: 173162			PRODUCT CUSTOMER DRAWING		
	▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DRWN: RYANAIDANI 2018/03/07			DOCUMENT NUMBER		
▽ = 0	ANGULAR TOL ± 3.0°		CHK'D: ASHIMOTSU 2018/03/07			DOC TYPE DOC PART REVISION			
▽ = 0	4 PLACES ± 0.2		APPR: RTAKEUCHI 2018/03/07			539840681 PSD 000 A			
▽ = 0	3 PLACES ± 0.2		INITIAL REVISION:			MATERIAL NUMBER			
▽ = 0	2 PLACES ± 0.2		DRWN: KTAKEUCHI01 2017/12/19			CUSTOMER			
▽ = 0	1 PLACE ± 0.2		APPR: RTAKEUCHI 2018/03/07			SHEET NUMBER			
▽ = 0	0 PLACES ± 0.2		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			1 OF 2			
□ = 0	THIRD ANGLE PROJECTION		DRAWING		SERIES		A3-SIZE 53984		

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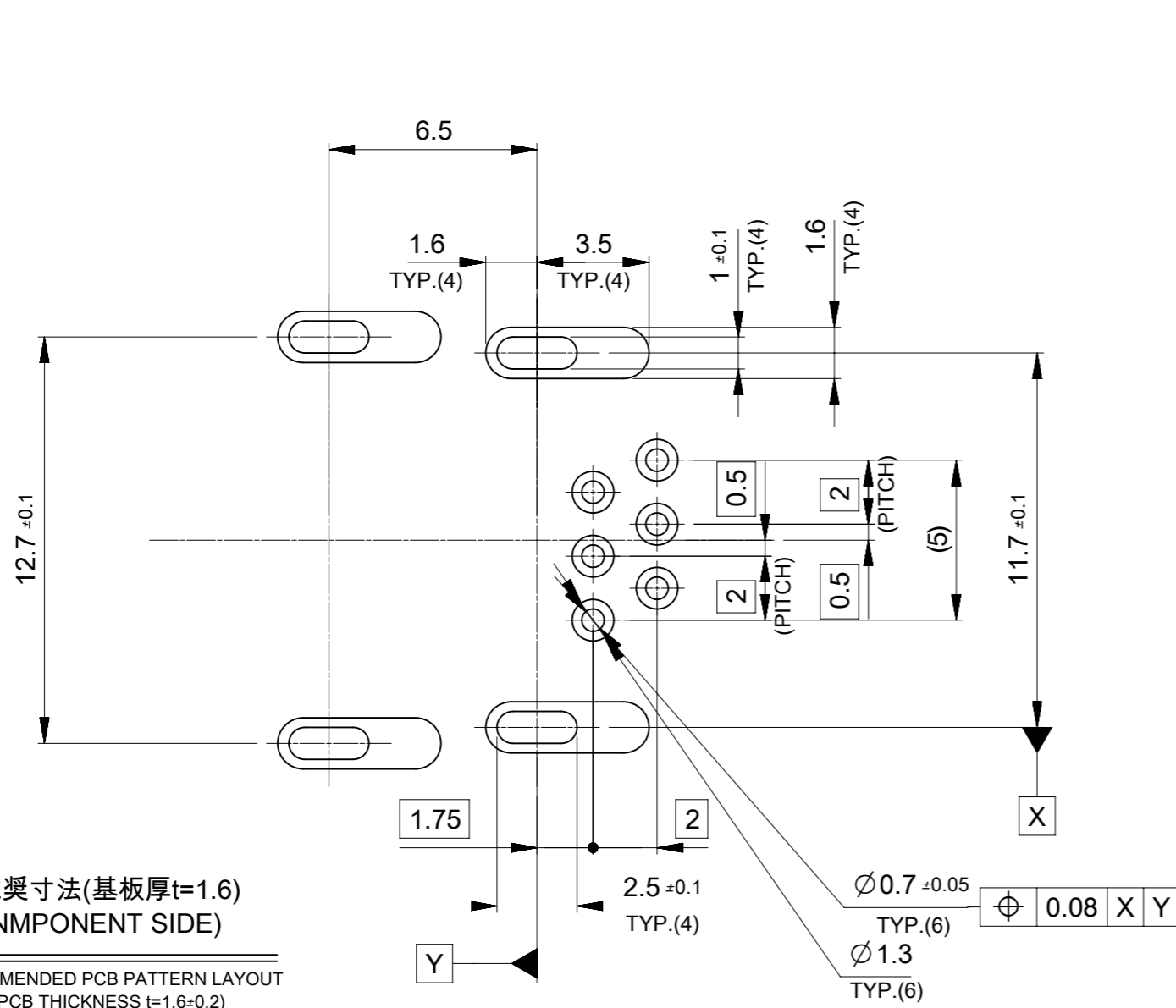
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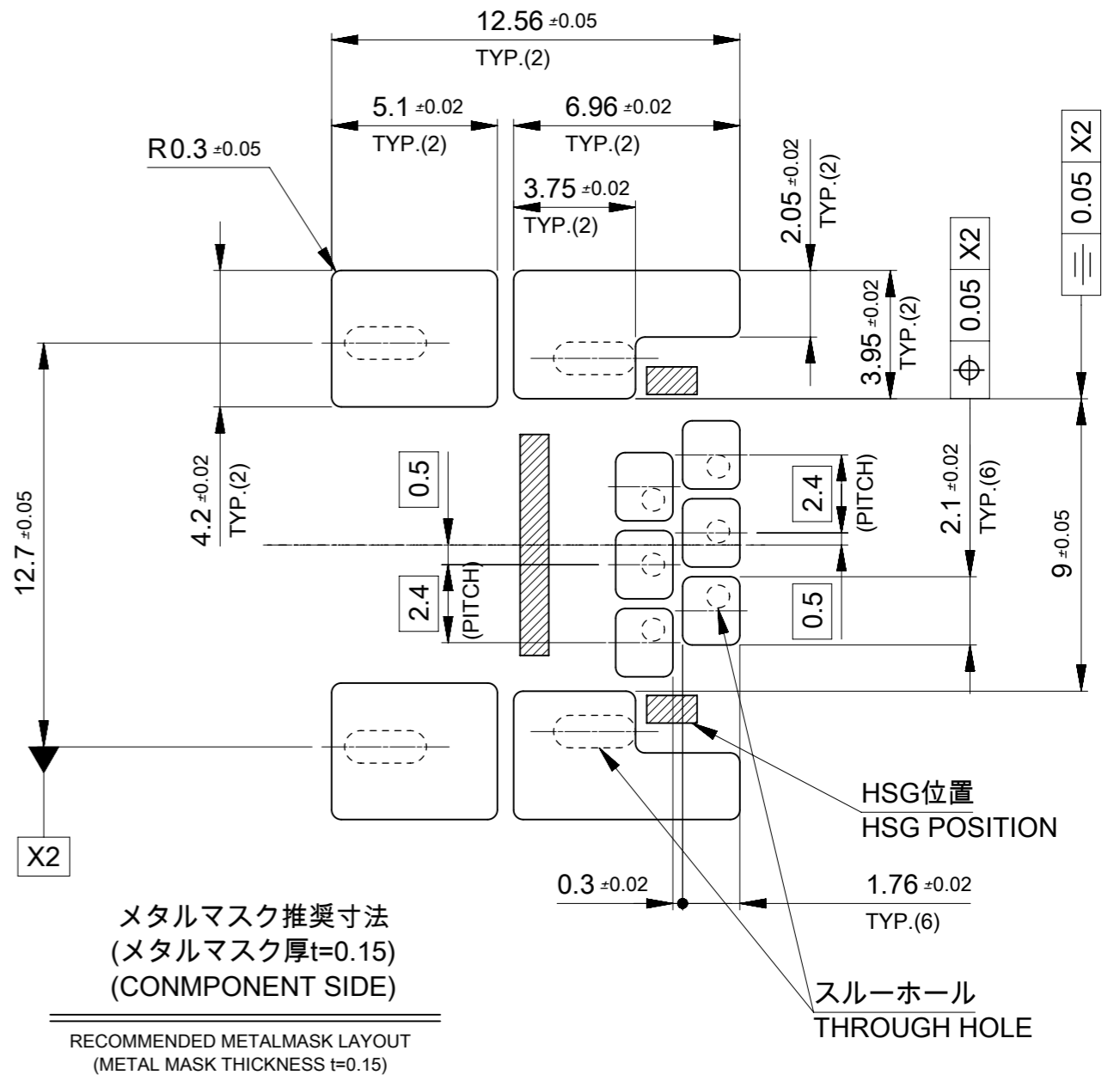
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基板推奨寸法(基板厚t=1.6)
(COMPONENT SIDE)
RECOMMENDED PCB PATTERN LAYOUT
(PCB THICKNESS t=1.6±0.2)



メタルマスク推奨寸法
(メタルマスク厚t=0.15)
(COMPONENT SIDE)
RECOMMENDED METAL MASK LAYOUT
(METAL MASK THICKNESS t=0.15)

SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC:		molex			
	DIMENSION UNITS	SCALE						2.0 I/O SOCKET RIGHT ANGLE -LEAD FREE-
	mm	5:1	GENERAL TOLERANCES (UNLESS SPECIFIED)			PRODUCT CUSTOMER DRAWING		
	ANGULAR TOL	± 3.0°	EC NO: 173162			DOCUMENT NUMBER		
4 PLACES	± 0.2	DRWN: RYANAIDANI 2018/03/07			539840681			
3 PLACES	± 0.2	CHK'D: ASHIMOTSU 2018/03/07			DOC TYPE			
2 PLACES	± 0.2	APPR: RTAKEUCHI 2018/03/07			PSD			
1 PLACE	± 0.2	INITIAL REVISION:			DOC PART			
0 PLACES	± 0.2	DRWN: KTAKEUCHI01 2017/12/19			000			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRAWING		SERIES		
		A3-SIZE		53984		REVISION		
						A		
						SHEET NUMBER		
						2 OF 2		